- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

description

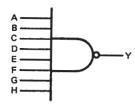
These devices contain a single 8-input NAND gate.

The SN5430, SN54LS30, and SN54S30 are characterized for operation over the full military range of $-55\,^{\circ}\text{C}$ to $125\,^{\circ}\text{C}$. The SN7430, SN74LS30, and SN74S30 are characterized for operation from $0\,^{\circ}\text{C}$ to $70\,^{\circ}\text{C}$.

FUNCTION TABLE

OUTPUT Y
L H

logic diagram

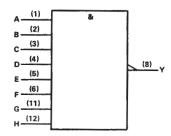


positive logic

$$Y = \overline{A \cdot B \cdot C \cdot D \cdot E \cdot F \cdot G \cdot H} \quad \text{or}$$

$$Y = \overline{A} + \overline{B} + \overline{C} + \overline{D} + \overline{E} + \overline{F} + \overline{G} + \overline{H}$$

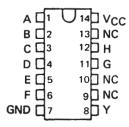
logic symbol†



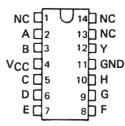
[†]This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

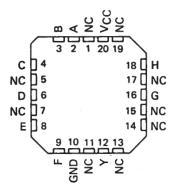
SN5430 . . . J PACKAGE
SN54LS30, SN54S30 . . . J OR W PACKAGE
SN7430 . . . N PACKAGE
SN74LS30, SN74S30 . . . D OR N PACKAGE
(TOP VIEW)



SN5430 . . . W PACKAGE (TOP VIEW)

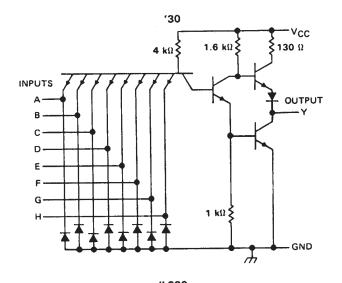


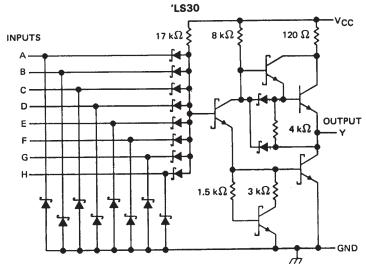
SN54LS30, SN54S30 . . . FK PACKAGE (TOP VIEW)

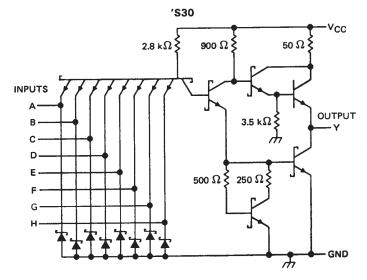


NC - No internal connection

schematics (each gate)







Resistor values shown are nominal.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	 7 V
Input voltage	 5.5 V
Operating free-air temperature range: SN5430	 -55°C to 125°C
SN7430	 0°C to 70°C
Storage temperature range	 -65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

			S	N5430			SN7430	0	
		MIN	V	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5	5.5	4.75	5	5.25	V
ViH	High-level input voltage		2			2			V
VIL	Low-level input voltage				8.0			0.8	V
Іон	High-level output current				- 0.4			- 0.4	mA
IOL	Low-level output current				16			16	mA
TA	Operating free-air temperature	- 59	5		125	0		70	°c

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	TEST CONDITIONS †			SN5430			SN7430			
PARAMETER	TES	TEST CONDITIONS (MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIK	V _{CC} = MIN, I _I =	– 12 mA				- 1.5			1.5	V
Voн	V _{CC} = MIN, V _{IL}	= 0.8 V,	1 _{OH} = − 0.4 mA	2.4	3.4		2.4	3.4		V
VOL	V _{CC} = MIN, V _I	4 = 2 V,	I _{OL} = 16 mA		0.2	0.4		0.2	0.4	V
l ₁	V _{CC} = MAX, V _i =	= 5.5 V				1			1	mA
¹ ІН	V _{CC} = MAX, V _I =	= 2.4 V				40			40	μА
I _{IL}	V _{CC} = MAX, V _I =	= 0.4 V				- 1.6			- 1.6	mA
I _{OS} §	V _{CC} = MAX			- 20		- 55	- 18		- 55	mA
Іссн	V _{CC} = MAX, V _I :	= 0			. 1	2		1	2	mA
1CCL	V _{CC} = MAX, V _I	= 4.5 V			3	6		3	6	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	ТҮР	MAX	UNIT
tpLH					13	22	ns
tPHL	Any	Y	$R_L = 400 \Omega$, $C_L = 15 pF$		8	15	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[§] Not more than one output should be shorted at a time.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)		7 V
Input voltage		7 V
Operating free-air temperature range:	SN54LS30	55°C to 125°C
	SN74LS30	

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

			SN54LS	30] :	SN74LS	30	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	ONII
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	٧
VIH	High-level input voltage	2	· · · · · · · · · · · · · · · · · · ·		2			٧
VIL	Low-level input voltage			0.7			8.0	٧
ЮН	High-level output current			- 0.4			- 0.4	mA
lOL	Low-level output current			4			8	mA
TA	Operating free-air temperature	- 55		125	0		70	°c

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

					SN54LS	30		UNIT		
PARAMETER		TEST CONDITIONS †		MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIK	V _{CC} = MIN,	I ₁ = - 18 mA				- 1.5			– 1.5	٧
Voн	V _{CC} = MIN,	VIL = MAX,	I _{OH} = - 0.4 mA	2.5	3.4		2.7	3.4		٧
	V _{CC} = MIN,	V _{IH} = 2 V,	I _{OL} = 4 mA		0.25	0.4			0.4	
VOL	V _{CC} = MIN,	V _{1H} = 2 V,	I _{OL} = 8 mA					0.25	0.5	
. II	V _{CC} = MAX,	V ₁ = 7 V				0.1			0.1	mA
Чн	V _{CC} = MAX,	V _I = 2.7 V				20			20	μА
IIL	V _{CC} = MAX,	V ₁ = 0.4 V				- 0.4			- 0.4	mA
I _{OS} §	V _{CC} = MAX			- 20		- 100	- 20		– 100	mA
Іссн	V _{CC} = MAX,	V _I = 0			0.35	0.5		0.35	0.5	mA
ICCL	V _{CC} = MAX,	V _I = 4.5 V			0.6	1.1		0.6	1.1	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, VCC = 5 V, TA = 25°C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
tPLH	Any	V	R _L = 2 kΩ, C _L = 15 pF		8	15	ns
t _{PHL}	Ally	'	$R_L = 2 k\Omega$, $C_L = 15 pF$		13	20	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

[§] Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	7 V
Input voltage	5.5 V
Operating free-air temperature range: SN54S30	-55°C to 125°C
SN74S30	
Storage temperature range	

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		SN54S3	10		SN74S	30	UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	ONT
V _{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	٧
VIH High-level input voltage	2			2			٧
VIL Low-level input voltage			0.8			8.0	٧
IOH High-level output current			- 1			- 1	mA
IOL Low-level output current			20			20	mA
TA Operating free-air temperature	55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		SN54S30	SN74S30	UNIT
PARAMETER	TEST CONDITIONS †	MIN TYP‡ MAX	MIN TYP\$ MAX	ONT
VIK	V _{CC} = MIN, I _I = -18 mA	-1.2	-1.2	٧
V _{OH}	V _{CC} = MIN, V _{IL} = 0.8 V, I _{OH} = -1 mA	2.5 3.4	2.7 3.4	٧
VOL	V _{CC} = MIN, V _{IH} = 2 V, I _{OL} = 20 mA	0.5	0.5	V
1,	V _{CC} = MAX, V _I = 5.5 V	1	1	mA
Iн	V _{CC} = MAX, V _I = 2.7 V	50	50	μΑ
IIL	V _{CC} = MAX, V _I = 0.5 V	-2	-2	mA
IOS §	V _{CC} = MAX	-40 -100	-40 -100	mA
Іссн	V _{CC} = MAX, V _I = 0	3 5	3 5	mA
1CCL	V _{CC} = MAX, V _I = 4.5 V	5.5 10	5.5 10	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, VCC = 5 V, TA = 25°C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	DITIONS	MIN TY	P MAX	UNIT
^t PLH			D 290 O	CL = 15 pF		4 6	ns
^t PHL			$R_L = 280 \Omega$,	C[- 13 pi	4.	5 7	ns
^t PLH	Any	Y	Υ	5.	5	ns	
^t PHL			$R_L = 280 \Omega$,	C _L = 50 pF	6.	5	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$. § Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.





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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9679201Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9679201Q2A SNJ54S 30FK	Samples
5962-9679201QCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9679201QC A SNJ54S30J	Samples
5962-9679201QCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9679201QC A SNJ54S30J	Samples
5962-9679201QDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9679201QD A SNJ54S30W	Samples
5962-9679201QDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9679201QD A SNJ54S30W	Samples
JM38510/30009B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30009B2A	Samples
JM38510/30009B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30009B2A	Samples
JM38510/30009BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30009BCA	Samples
JM38510/30009BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30009BCA	Samples
JM38510/30009BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30009BDA	Samples
JM38510/30009BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30009BDA	Samples
JM38510/30009SCA	ACTIVE	CDIP	J	14	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30009SCA	Samples
JM38510/30009SCA	ACTIVE	CDIP	J	14	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30009SCA	Samples
JM38510/30009SDA	ACTIVE	CFP	W	14	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30009SDA	Samples





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Orderable Device	Status	Package Type		Pins		Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Sample
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
JM38510/30009SDA	ACTIVE	CFP	W	14	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30009SDA	Sample
M38510/30009B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30009B2A	Sample
M38510/30009B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30009B2A	Sample
M38510/30009BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30009BCA	Sample
M38510/30009BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30009BCA	Sample
M38510/30009BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30009BDA	Sampl
M38510/30009BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30009BDA	Sampl
M38510/30009SCA	ACTIVE	CDIP	J	14	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30009SCA	Sampl
M38510/30009SCA	ACTIVE	CDIP	J	14	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30009SCA	Sampl
M38510/30009SDA	ACTIVE	CFP	W	14	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30009SDA	Sampl
M38510/30009SDA	ACTIVE	CFP	W	14	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30009SDA	Sampl
SN5430J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN5430J	Sampl
SN5430J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN5430J	Sampl
SN54LS30J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS30J	Sampl
SN54LS30J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS30J	Sampl
SN54S30J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54S30J	Samp
SN54S30J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54S30J	Samp
SN7430N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN7430N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74LS30D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS30	Samp



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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LS30D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS30	Samples
SN74LS30DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS30	Samples
SN74LS30DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS30	Samples
SN74LS30DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS30	Samples
SN74LS30DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS30	Samples
SN74LS30J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	0 to 70		
SN74LS30J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	0 to 70		
SN74LS30N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS30N	Samples
SN74LS30N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS30N	Samples
SN74LS30N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74LS30N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74LS30NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS30N	Samples
SN74LS30NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS30N	Samples
SN74LS30NSR	ACTIVE	so	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS30	Samples
SN74LS30NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS30	Samples
SN74S30D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70		
SN74S30D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70		
SN74S30DR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70		
SN74S30DR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70		
SN74S30J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	0 to 70		
SN74S30J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	0 to 70		
SN74S30N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74S30N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		





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Orderable Device	Status	Package Type		Pins	_	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SNJ5430J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ5430J	Samples
SNJ5430J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ5430J	Samples
SNJ5430W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ5430W	Samples
SNJ5430W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ5430W	Samples
SNJ54LS30FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS 30FK	Samples
SNJ54LS30FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS 30FK	Samples
SNJ54LS30J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS30J	Samples
SNJ54LS30J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS30J	Samples
SNJ54LS30W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS30W	Samples
SNJ54LS30W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS30W	Samples
SNJ54S30FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9679201Q2A SNJ54S 30FK	Samples
SNJ54S30FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9679201Q2A SNJ54S 30FK	Samples
SNJ54S30J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9679201QC A SNJ54S30J	Samples
SNJ54S30J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9679201QC A SNJ54S30J	Samples
SNJ54S30W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9679201QD A SNJ54S30W	Samples
SNJ54S30W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9679201QD A SNJ54S30W	Samples

PACKAGE OPTION ADDENDUM



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(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN5430, SN54LS30, SN54LS30-SP, SN54S30, SN7430, SN74LS30, SN74S30:

Catalog: SN7430, SN74LS30, SN54LS30, SN74S30

Military: SN5430, SN54LS30, SN54S30





10-Jun-2014

• Space: SN54LS30-SP

NOTE: Qualified Version Definitions:

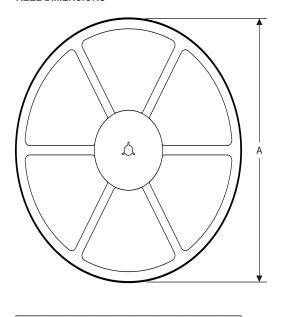
- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications
- Space Radiation tolerant, ceramic packaging and qualified for use in Space-based application

PACKAGE MATERIALS INFORMATION

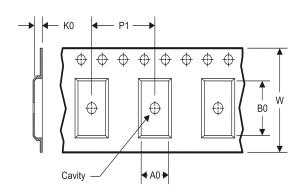
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TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device Lackage Lackage									P1	W	Pin1		
		туре	Drawing				W1 (mm)	(mm)	(mm)	(mm)	(mm)	(mm)	Quadrant
	SN74LS30DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
	SN74LS30NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS30DR	SOIC	D	14	2500	367.0	367.0	38.0
SN74LS30NSR	SO	NS	14	2000	367.0	367.0	38.0

14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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